

## **23V, 3A, 650KHz Synchronous Step-Down DC/DC Converter**

### **Description**

The FR8209 is a synchronous step-down DC/DC converter that provides wide 4.5V to 23V input voltage range and 3A continuous load current capability. At light load condition, the FR8209 can operate at PSM mode to support high efficiency and reduce power loss.

The FR8209 fault protection includes cycle-by-cycle current limit, UVLO, output overvoltage protection and thermal shutdown. The adjustable soft-start function prevents inrush current at turn-on. This device uses current mode control scheme which provides fast transient response. Internal Compensation function reduces external compensation components and simplifies the design process. In shutdown mode, the supply current is about 1 $\mu$ A.

The FR8209 is available in a SOP-8 exposed pad package, which provides good thermal conductance.

### **Features**

- High Efficiency up to 95%
- Low Rds(on) Integrated Power MOSFET
- Internal Compensation Function
- Internal Power Good Function
- Wide Input Voltage Range: 4.5V to 23V
- Adjustable Output Voltage Down to 0.765V
- 3A Output Current
- Fixed 650KHz Switching Frequency
- External Programmable Soft-Start or Internal 600 $\mu$ s Soft-Start
- PSM (High Efficiency at Light Load)
- Cycle-by-Cycle Current Limit
- Over-Temperature Protection with Auto Recovery
- OVP, UVLO, OTP
- Hiccup Short Circuit Protect
- SOP-8 Exposed Pad Package

### **Applications**

- STB (Set-Top-Box)
- LCD Displays, TV
- Distributed Power System
- Networking, XDSL Modem

### **Pin Assignments**

**SP Package (SOP-8 Exposed Pad)**

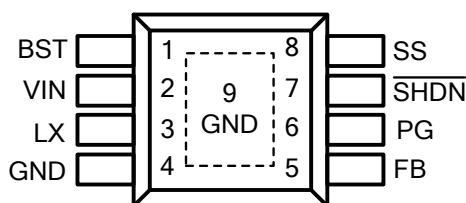
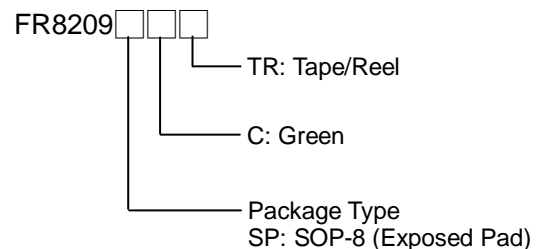


Figure 1. Pin Assignment of FR8209

### **Ordering Information**



**Typical Application Circuit**

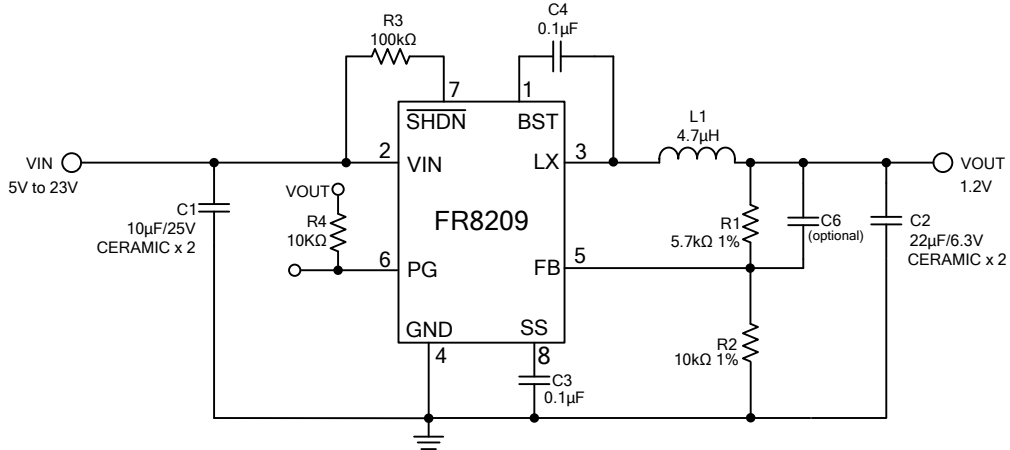


Figure 2. C<sub>IN</sub>/C<sub>OUT</sub> use Ceramic Capacitors Application Circuit

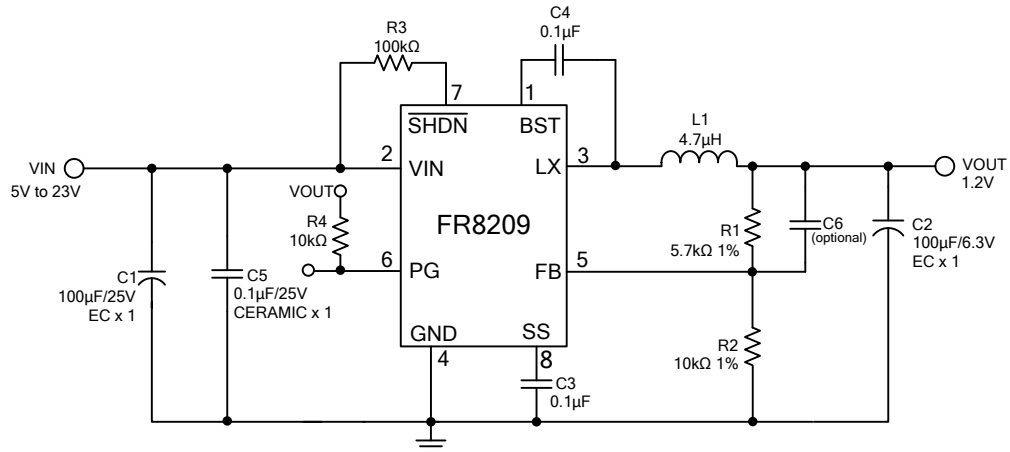


Figure 3. C<sub>IN</sub>/C<sub>OUT</sub> use Electrolytic Capacitors Application Circuit

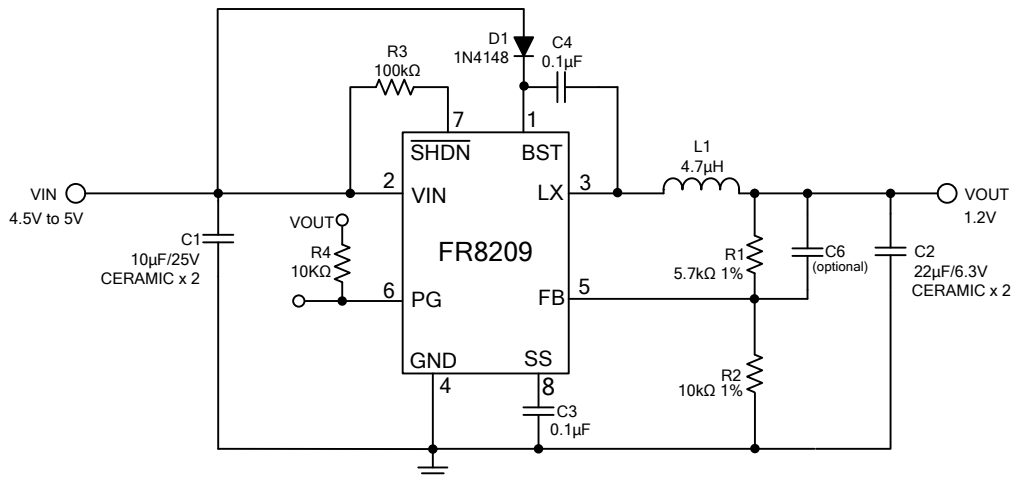


Figure 4. Low Input Voltage Application Circuit

## Functional Pin Description

Pin Name	Pin No.	I/O	Pin Function
FB	5	I	Voltage Feedback Input Pin. Connect FB and $V_{OUT}$ with a resistive voltage divider. This IC senses feedback voltage via FB and regulates it at 0.765V.
VIN	2	I	Power Supply Input Pin. Drive VIN pin by 4.5V to 23V voltage to power on the chip.
$\overline{\text{SHDN}}$	7	I	Enable Input Pin. This pin is a digital control input that turns the converter on or off. Connect to VIN with a 100K $\Omega$ resistor for self-startup.
GND	4	I	Ground Pin. Connect GND to exposed pad.
LX	3	O	Power Switching Output. LX is the output of the internal high side NMOS switch.
SS	8	O	Soft-Start Pin. SS controls the soft-start period. Connect a capacitor from SS to GND to set the soft start period.
BST	1	O	High Side Gate Drive Boost Pin. A capacitor rating between 10nF~100nF must be connected from this pin to LX. It can boost the gate drive to fully turn on the internal high side NMOS.
PG	6	O	Open Drain Power Good Output Pin.

## Block Diagram

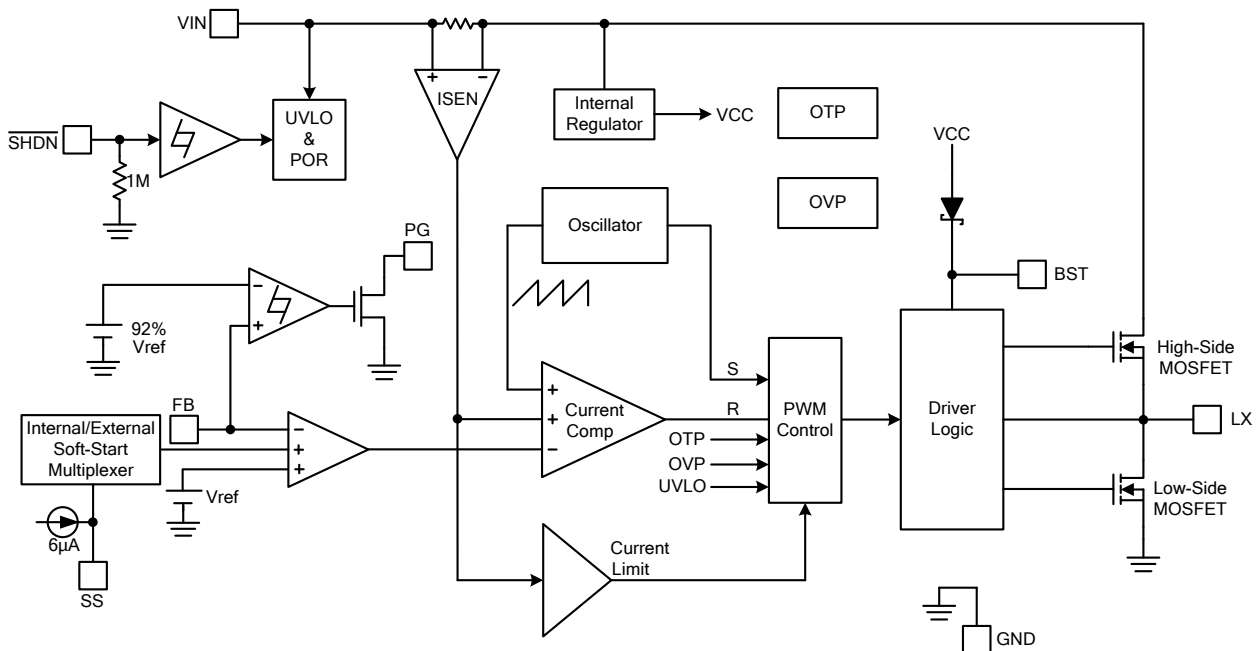


Figure 5. Block Diagram of FR8209

## Absolute Maximum Ratings (Note 1)

- Supply Voltage  $V_{IN}$  ----- -0.3V to +25V
- Enable Voltage  $V_{\overline{SHDN}}$  ----- -0.3V to +25V
- LX Voltage  $V_{LX}$  ----- -1V to  $V_{IN}+0.3V$
- BST Pin Voltage  $V_{BST}$  -----  $V_{LX}-0.3V$  to  $V_{LX}+6V$
- All Other Pins Voltage ----- -0.3V to +6V
- Maximum Junction Temperature ( $T_J$ ) ----- +150°C
- Storage Temperature ( $T_S$ ) ----- -65°C to +150°C
- Lead Temperature (Soldering, 10sec.) ----- +260°C
- Package Thermal Resistance, ( $\theta_{JA}$ ) (Note 2)
  - SOP-8 (Exposed Pad) ----- 60°C/W
- Package Thermal Resistance, ( $\theta_{JC}$ )
  - SOP-8 (Exposed Pad) ----- 15°C/W

Note 1 : Stresses beyond this listed under "Absolute Maximum Ratings" may cause permanent damage to the device.

Note 2 : PCB heat sink copper area = 10mm<sup>2</sup>.

## Recommended Operating Conditions

- Supply Voltage  $V_{IN}$  ----- +4.5V to +23V
- Enable Voltage  $V_{\overline{SHDN}}$  ----- 0V to  $V_{IN}$
- Operation Temperature Range ----- -40°C to +85°C

## Electrical Characteristics

( $V_{IN}=12V$ ,  $T_A=25^{\circ}C$ , unless otherwise specified.)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
$V_{IN}$ Input Supply Voltage	$V_{IN}$		4.5		23	V
$V_{IN}$ Quiescent Current	$I_{DDQ}$	$V_{\overline{SHDN}}=1.8V$ , $V_{FB}=1.0V$		2		mA
$V_{IN}$ Shutdown Supply Current	$I_{SD}$	$V_{\overline{SHDN}}=0V$		1	10	$\mu A$
Feedback Voltage	$V_{FB}$	$4.5V \leq V_{IN} \leq 23V$	0.749	0.765	0.781	V
High-Side MOSFET $R_{DS(ON)}$ (Note3)	$R_{DS(ON)}$			120		m $\Omega$
Low-Side MOSFET $R_{DS(ON)}$ (Note3)	$R_{DS(ON)}$			100		m $\Omega$
High-Side MOSFET Leakage Current	$I_{LX(leak)}$	$V_{\overline{SHDN}}=0V$ , $V_{LX}=0V$			10	$\mu A$
High-Side MOSFET Current Limit (Note3)	$I_{LIMIT(HS)}$	Minimum Duty	4.5	5.5		A
Oscillation Frequency	$F_{OSC}$		550	650	750	KHz
Short Circuit Oscillation Frequency	$F_{OSC(short)}$	$V_{FB}=0V$		150		KHz
Maximum Duty Cycle	$D_{MAX}$	$V_{FB}=0.6V$		80		%
Minimum On Time (Note3)	$T_{MIN}$			110		ns
Input Supply Voltage UVLO Threshold	$V_{UVLO(Vth)}$	$V_{IN}$ Rising		4.2		V
Input Supply Voltage UVLO Threshold Hysteresis	$V_{UVLO(HYS)}$			400		mV
Soft-Start Current	$I_{SS}$	$V_{SS}=0V$		6		$\mu A$
External Soft-Start Period	$T_{SS}$	$C_{SS}=0.1\mu F$		12.75		ms
Internal Soft-Start Period	$T_{SS}$			600		$\mu s$
PG High Threshold	$V_{PG(H)}$	$V_{FB}$ rising		92		%
PG Low Threshold	$V_{PG(L)}$	$V_{FB}$ falling		82		%
PG Sink Current	$I_{PG}$	$V_{PG}=0.3V$		1		mA
$\overline{SHDN}$ Input Low Voltage	$V_{\overline{SHDN}(L)}$				0.4	V
$\overline{SHDN}$ Input High Voltage	$V_{\overline{SHDN}(H)}$		2			V
$\overline{SHDN}$ Input Current	$I_{\overline{SHDN}}$	$V_{\overline{SHDN}}=2V$		2		$\mu A$
Thermal Shutdown Threshold (Note3)	$T_{SD}$			165		$^{\circ}C$

Note 3 : Not production tested.

### Typical Performance Curves

$V_{IN}=12V$ ,  $V_{OUT}=3.3V$ ,  $C1=10\mu F \times 2$ ,  $C2=22\mu F \times 2$ ,  $L1=4.7\mu H$ ,  $T_A=+25^\circ C$ , unless otherwise noted.

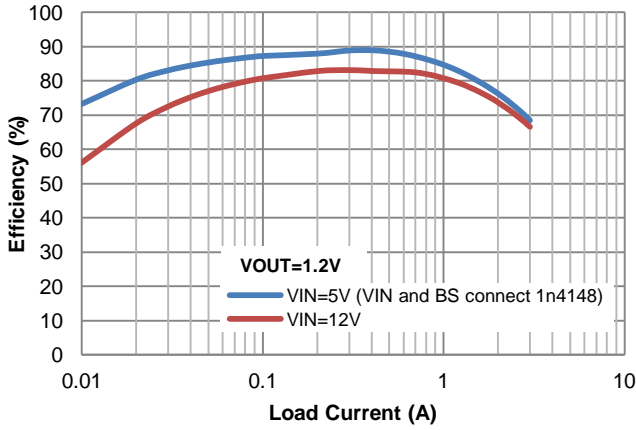


Figure 6. Efficiency vs. Load Current

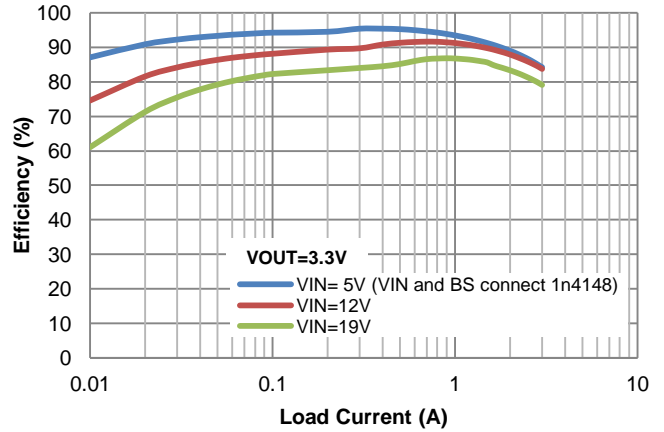


Figure 7. Efficiency vs. Load Current

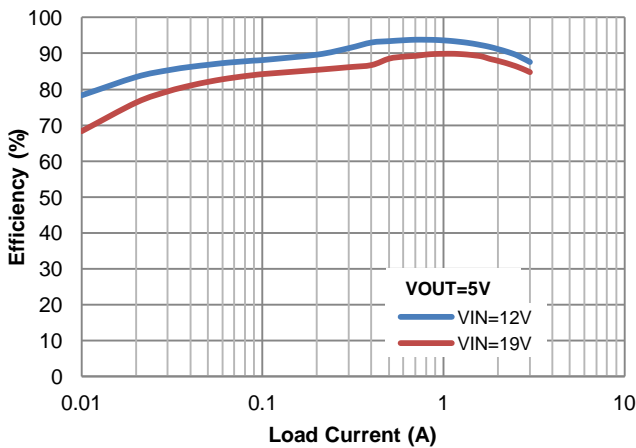


Figure 8. Efficiency vs. Load Current

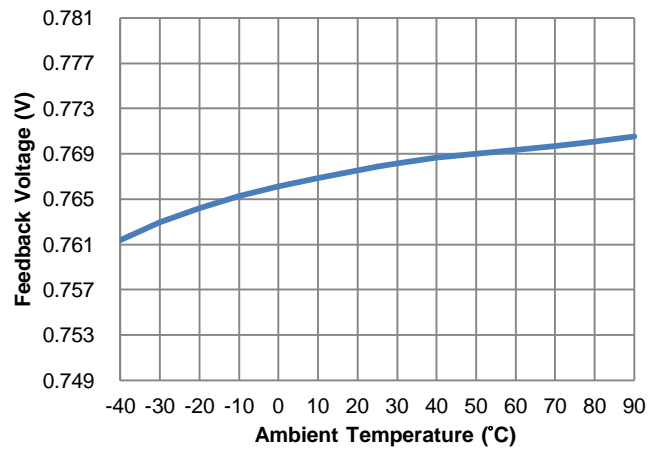


Figure 9. Feedback Voltage vs. Temperature

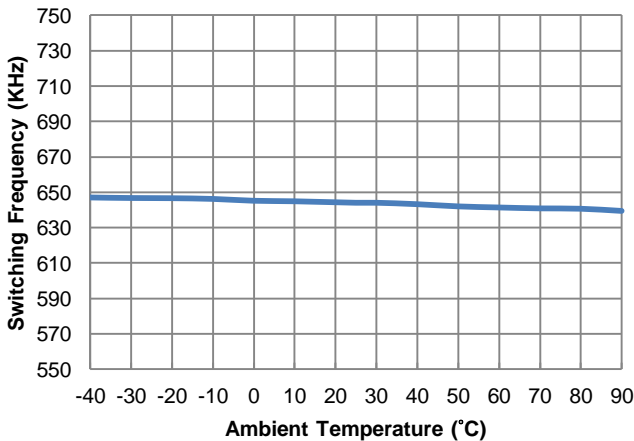


Figure 10. Switching Frequency vs. Temperature

### Typical Performance Curves (Continued)

$V_{IN}=12V$ ,  $V_{OUT}=3.3V$ ,  $C1=10\mu F \times 2$ ,  $C2=22\mu F \times 2$ ,  $L1=4.7\mu H$ ,  $T_A=+25^\circ C$ , unless otherwise noted.

$I_{OUT}=0A$

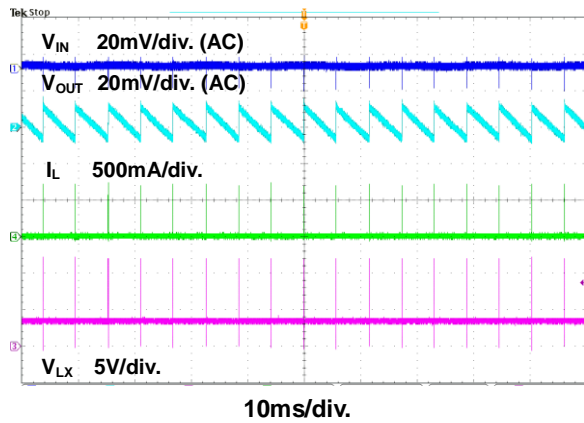


Figure 11. Steady State Waveform

$I_{OUT}=3A$

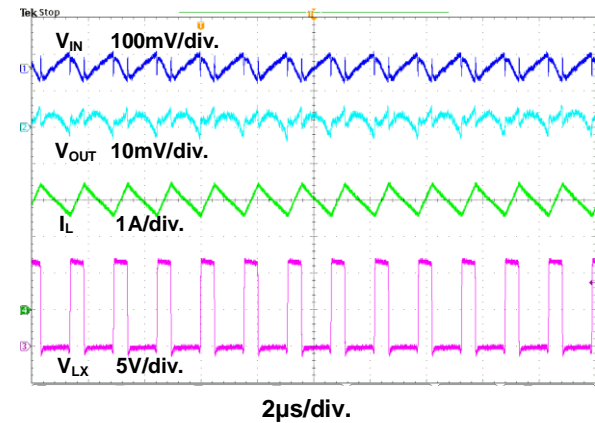


Figure 12. Steady State Waveform

$I_{OUT}=0A$

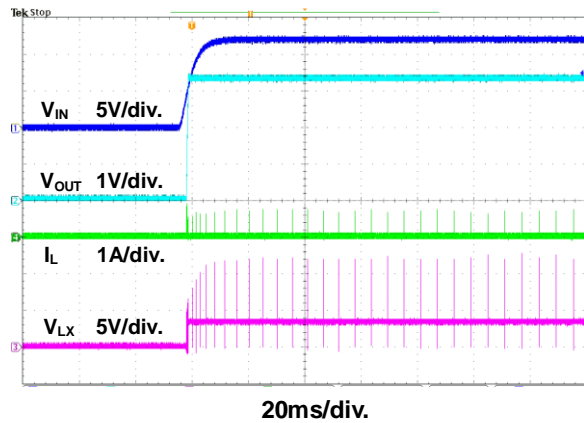


Figure 13. Power On through VIN Waveform

$I_{OUT}=3A$

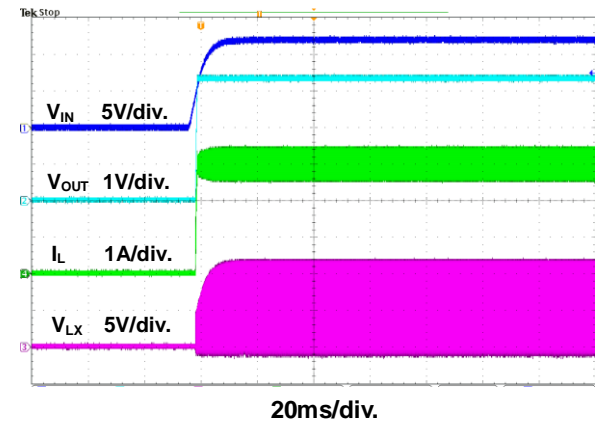


Figure 14. Power On through VIN Waveform

$I_{OUT}=0A$

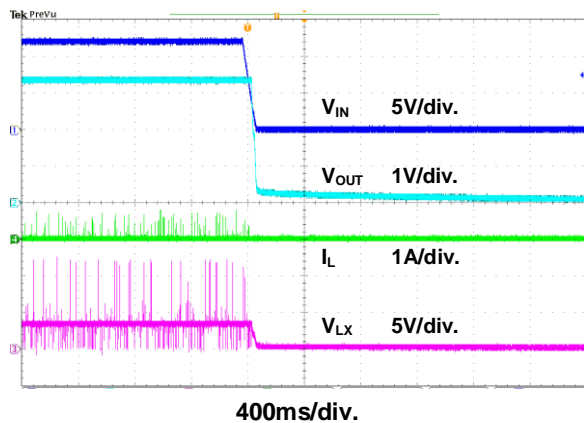


Figure 15. Power Off through VIN Waveform

$I_{OUT}=3A$

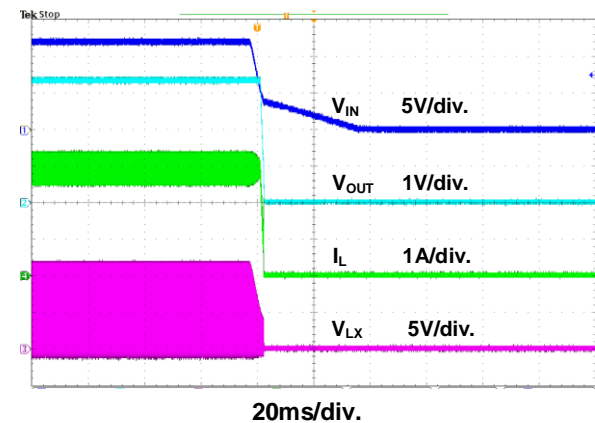


Figure 16. Power Off through VIN Waveform

### Typical Performance Curves (Continued)

$V_{IN}=12V$ ,  $V_{OUT}=3.3V$ ,  $C1=10\mu F \times 2$ ,  $C2=22\mu F \times 2$ ,  $L1=4.7\mu H$ ,  $T_A=+25^\circ C$ , unless otherwise noted.

$I_{OUT}=0A$

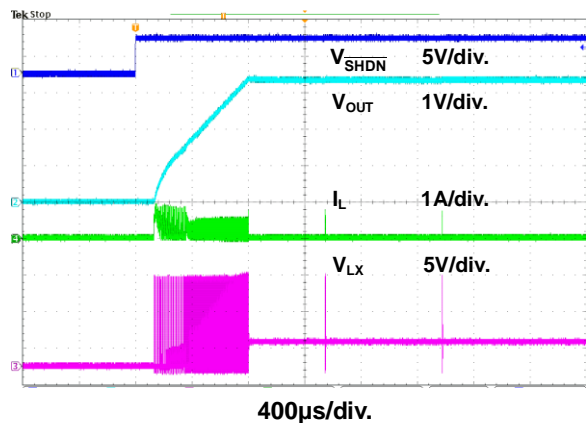


Figure 17. Power On through  $\overline{SHDN}$  Waveform

$I_{OUT}=3A$

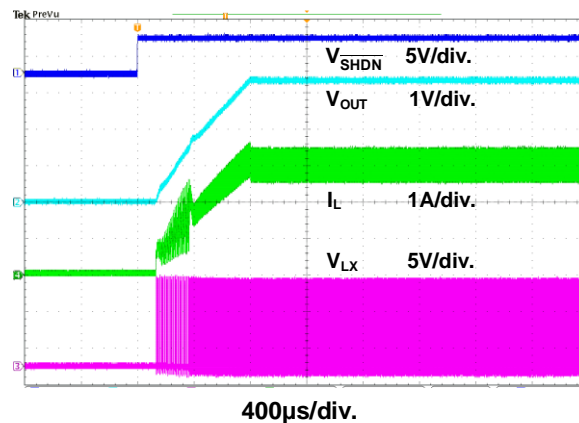


Figure 18. Power On through  $\overline{SHDN}$  Waveform

$I_{OUT}=0A$

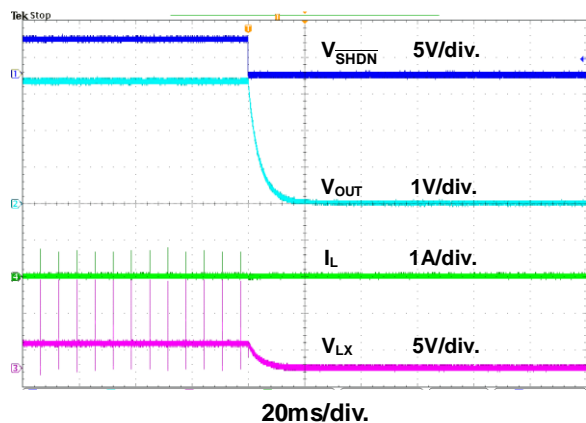


Figure 19. Power Off through  $\overline{SHDN}$  Waveform

$I_{OUT}=3A$

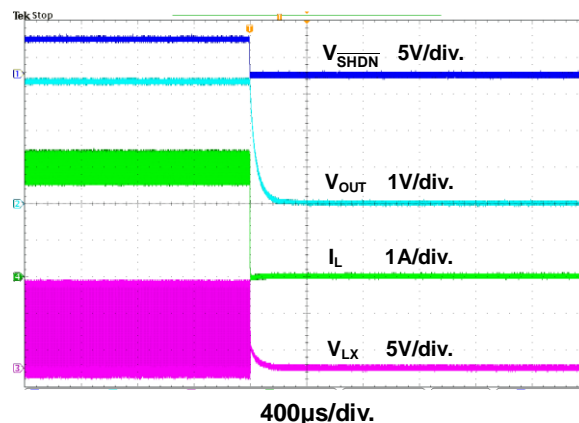


Figure 20. Power Off through  $\overline{SHDN}$  Waveform

$I_{OUT}=0.1A$  to  $3A$

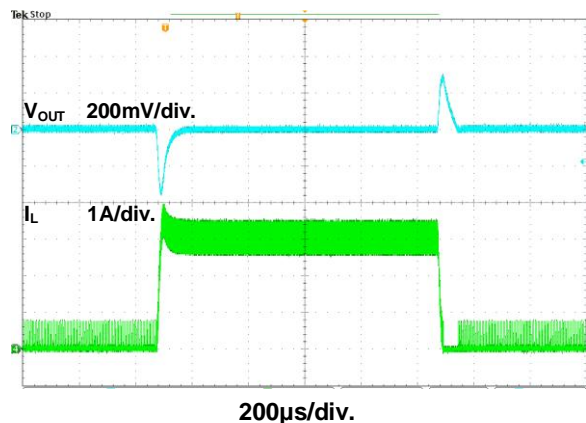


Figure 21. Load Transient Waveform

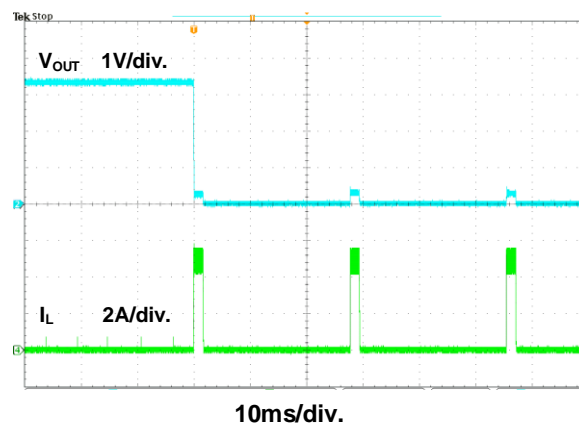


Figure 22. Short Circuit Test



## Function Description

The FR8209 is a high efficiency, internal compensation and constant frequency current mode step-down synchronous DC/DC converter. It has integrated high-side (120mΩ, typ) and low-side (100mΩ, typ) power switches, and provides 3A continuous load current. It regulates input voltage from 4.5V to 23V, and down to an output voltage as low as 0.765V.

### Control Loop

Under normal operation, the output voltage is sensed by FB pin through a resistive voltage divider and amplified through the error amplifier. The voltage of error amplifier output is compared to the switch current to control the RS latch. At the beginning of each clock cycle, the high-side NMOS will turn on when the oscillator sets the RS latch, and turn off when current comparator resets the RS latch. Then the low-side NMOS will turn on until the clock period ends.

### $\overline{\text{SHDN}}$

The FR8209  $\overline{\text{SHDN}}$  pin provides digital control to turn on/turn off the regulator. When the voltage of  $\overline{\text{SHDN}}$  exceeds the threshold voltage, the regulator will start the soft start function. If the  $\overline{\text{SHDN}}$  pin voltage is below the shutdown threshold voltage, the regulator will turn into the shutdown mode and the shutdown current will be smaller than 1μA. For auto start-up operation, connect  $\overline{\text{SHDN}}$  to VIN through a 100KΩ resistor.

### Soft Start

The FR8209 employs internal and programmable external soft start functions to reduce input inrush current during start up. When SS pin doesn't connect to C<sub>SS</sub> capacitor, the internal soft start time will be 600μs. When SS pin connects to C<sub>SS</sub> capacitor, the C<sub>SS</sub> capacitor will be charged by a 6μA current. The equation for the soft start time is shown as below:

$$T_{SS}(\text{ms}) = \frac{C_{SS}(\text{nF}) \times V_{FB}}{I_{SS}(\mu\text{A})}$$

The V<sub>FB</sub> voltage is 0.765V and the I<sub>SS</sub> current is 6μA. If a 0.1μF capacitor is connected from SS pin to GND, the soft start time will be 12.75ms.

### Output Over Voltage Protection

When the FB pin voltage exceeds 1.25V, the output over voltage protection function will be triggered and turn off the high-side/low-side MOSFET.

### Input Under Voltage Lockout

When the FR8209 is power on, the internal circuits will be held inactive until V<sub>IN</sub> voltage exceeds the input UVLO threshold voltage. And the regulator will be disabled when V<sub>IN</sub> is below the input UVLO threshold voltage. The hysteresis of the UVLO comparator is 250mV (typ).

### Short Circuit Protection

The FR8209 provides short circuit protection function to prevent the device damage from short condition. When the short condition occurs and the feedback voltage drops lower than 0.4V, the oscillator frequency will be reduced to 110KHz and hiccup mode will be triggered to prevent the inductor current increasing beyond the current limit. Once the short condition is removed, the frequency will return to normal.

### Over Current Protection

The FR8209 over current protection function is implemented by using cycle-by-cycle current limit architecture. The inductor current is monitored by measuring the high-side MOSFET series sense resistor voltage. When the load current increases, the inductor current will also increase. When the peak inductor current reaches the current limit threshold, the output voltage will start to drop. When the over current condition is removed, the output voltage will return to the regulated value.

### Over Temperature Protection

The FR8209 incorporates an over temperature protection circuit to protect itself from overheating. When the junction temperature exceeds the thermal shutdown threshold temperature, the regulator will be shutdown. And the hysteresis of the over temperature protection is 50°C (typ).

### Internal Compensation Function

The stability of the feedback circuit is controlled through internal compensation circuits. This internal compensation function is optimized for most applications, and this function can reduce external R, C components.

## Application Information

### Output Voltage Setting

The output voltage  $V_{OUT}$  is set by using a resistive divider from the output to FB. The FB pin regulated voltage is 0.765V. Thus the output voltage is:

$$V_{OUT} = 0.765V \times \left(1 + \frac{R1}{R2}\right)$$

Table 2 lists recommended values of R1 and R2 for most used output voltage.

**Table 2 Recommended Resistance Values**

$V_{OUT}$	R1	R2
5V	59k $\Omega$	10.5k $\Omega$
3.3V	34.8k $\Omega$	10.5k $\Omega$
2.5V	23.7k $\Omega$	10.5k $\Omega$
1.8V	14.3k $\Omega$	10.5k $\Omega$
1.2V	6.04k $\Omega$	10.5k $\Omega$

Place resistors R1 and R2 close to FB pin to prevent stray pickup.

### Input Capacitor Selection

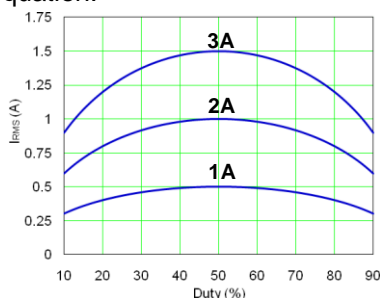
The use of the input capacitor is filtering the input voltage ripple and the MOSFETS switching spike voltage. Because the input current to the step-down converter is discontinuous, the input capacitor is required to supply the current to the converter to keep the DC input voltage. The capacitor voltage rating should be 1.25 to 1.5 times greater than the maximum input voltage. The input capacitor ripple current RMS value is calculated as:

$$I_{IN(RMS)} = I_{OUT} \times \sqrt{D \times (1-D)}$$

$$D = \frac{V_{OUT}}{V_{IN}}$$

Where D is the duty cycle of the power MOSFET.

This function reaches the maximum value at  $D=0.5$ , and the equivalent RMS current is equal to  $I_{OUT}/2$ . The following diagram is the graphical representation of above equation.



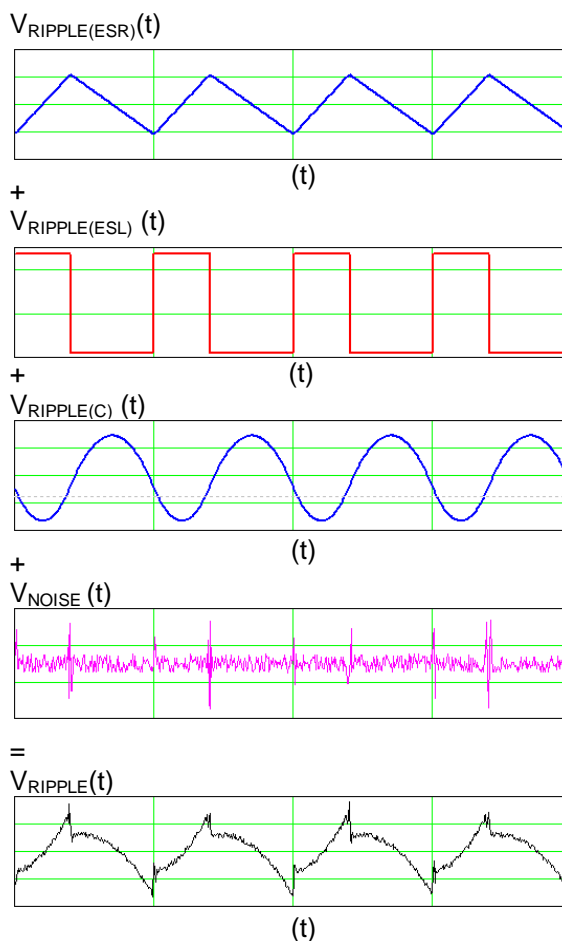
A low ESR capacitor is required to keep the noise minimum. Ceramic capacitors are better, but tantalum or low ESR electrolytic capacitors may also suffice. When using tantalum or electrolytic capacitors, a 0.1 $\mu$ F ceramic capacitor should be placed as close to the IC as possible.

### Output Capacitor Selection

The output capacitor is used to keep the DC output voltage and supply the load transient current. When operating in constant current mode, the output ripple is determined by four components:

$$V_{RIPPLE}(t) = V_{RIPPLE(C)}(t) + V_{RIPPLE(ESR)}(t) + V_{RIPPLE(ESL)}(t) + V_{NOISE}(t)$$

The following figures show the form of the ripple contributions.



**Application Information (Continued)**

$$V_{\text{RIPPLE(ESR, p-p)}} = \frac{V_{\text{OUT}}}{F_{\text{OSC}} \times L} \times \left(1 - \frac{V_{\text{OUT}}}{V_{\text{IN}}}\right) \times \text{ESR}$$

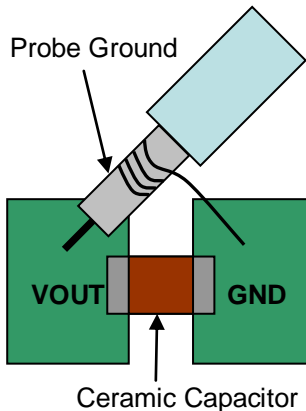
$$V_{\text{RIPPLE(ESL, p-p)}} = \frac{\text{ESL}}{L + \text{ESL}} \times V_{\text{IN}}$$

$$V_{\text{RIPPLE(C, p-p)}} = \frac{V_{\text{OUT}}}{8 \times F_{\text{OSC}}^2 \times L \times C_{\text{OUT}}} \times \left(1 - \frac{V_{\text{OUT}}}{V_{\text{IN}}}\right)$$

Where  $F_{\text{OSC}}$  is the switching frequency,  $L$  is the inductance value,  $V_{\text{IN}}$  is the input voltage, ESR is the equivalent series resistance value of the output capacitor, ESL is the equivalent series inductance value of the output capacitor and the  $C_{\text{OUT}}$  is the output capacitor.

Low ESR capacitors are preferred to use. Ceramic, tantalum or low ESR electrolytic capacitors can be used depending on the output ripple requirements. When using the ceramic capacitors, the ESL component is usually negligible.

It is important to use the proper method to eliminate high frequency noise when measuring the output ripple. The figure shows how to locate the probe across the capacitor when measuring output ripple. Remove the scope probe plastic jacket in order to expose the ground at the tip of the probe. It gives a very short connection from the probe ground to the capacitor and eliminating noise.



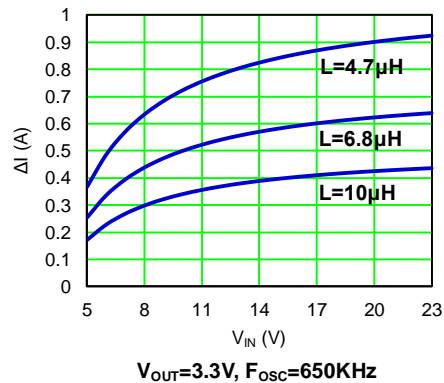
**Inductor Selection**

The output inductor is used for storing energy and filtering output ripple current. But the trade-off condition often happens between maximum energy storage and the physical size of the inductor. The first consideration for selecting the output inductor is to make sure that the inductance is large enough to keep the converter in the continuous current mode.

That will lower ripple current and result in lower output ripple voltage. The  $\Delta I_L$  is inductor peak-to-peak ripple current:

$$\Delta I = \frac{V_{\text{OUT}}}{F_{\text{OSC}} \times L} \times \left(1 - \frac{V_{\text{OUT}}}{V_{\text{IN}}}\right)$$

The following diagram is an example to graphical represent  $\Delta I_L$  equation.



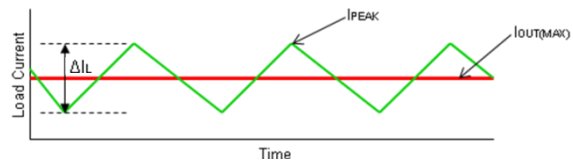
A good compromise value between size and efficiency is to set the peak-to-peak inductor ripple current  $\Delta I_L$  equal to 30% of the maximum load current. But setting the peak-to-peak inductor ripple current  $\Delta I_L$  between 20%~50% of the maximum load current is also acceptable. Then the inductance can be calculated with the following equation:

$$\Delta I = 0.3 \times I_{\text{OUT(MAX)}}$$

$$L = \frac{(V_{\text{IN}} - V_{\text{OUT}}) \times V_{\text{OUT}}}{V_{\text{IN}} \times F_{\text{OSC}} \times \Delta I_L}$$

To guarantee sufficient output current, peak inductor current must be lower than the FR8209 high-side MOSFET current limit. The peak inductor current is as below:

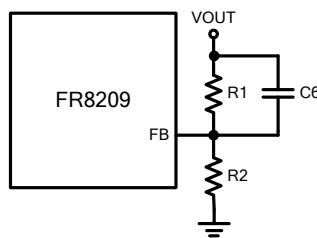
$$I_{\text{PEAK}} = I_{\text{OUT(MAX)}} + \frac{\Delta I_L}{2}$$



## Application Information (Continued)

### Feedforward Capacitor Selection

Internal compensation function allows users saving time in design and saving cost by reducing the number of external components. The use of a feedforward capacitor C6 in the feedback network is recommended to improve the transient response or higher phase margin.



For optimizing the feedforward capacitor, knowing the cross frequency is the first thing. The cross frequency (or the converter bandwidth) can be determined by using a network analyzer. When getting the cross frequency with no feedforward capacitor identified, the value of feedforward capacitor C6 can be calculated with the following equation:

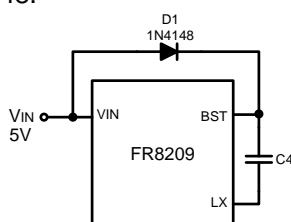
$$C6 = \frac{1}{2\pi \times F_{CROSS}} \times \sqrt{\frac{1}{R1} \times \left(\frac{1}{R1} + \frac{1}{R2}\right)}$$

Where  $F_{CROSS}$  is the cross frequency.

To reduce transient ripple, the feedforward capacitor value can be increased to push the cross frequency to higher region. Although this can improve transient response, it also decreases phase margin and causes more ringing. In the other hand, if more phase margin is desired, the feedforward capacitor value can be decreased to push the cross frequency to lower region. In general, the feedforward capacitor range is between 10pF to 1nF.

### External Diode Selection

For 5V input applications, it is recommended to add an external boost diode. This helps improving the efficiency. The boost diode can be a low cost one, such as 1N4148.



### PCB Layout Recommendation

The device's performance and stability are dramatically affected by PCB layout. It is recommended to follow these general guidelines shown as below:

1. Place the input capacitors and output capacitors as close to the device as possible. The traces which connect to these capacitors should be as short and wide as possible to minimize parasitic inductance and resistance.
2. Place feedback resistors close to the FB pin.
3. Keep the sensitive signal (FB) away from the switching signal (LX).
4. The exposed pad of the package should be soldered to an equivalent area of metal on the PCB. This area should connect to the GND plane and have multiple via connections to the back of the PCB as well as connections to intermediate PCB layers. The GND plane area connecting to the exposed pad should be maximized to improve thermal performance.
5. Multi-layer PCB design is recommended.

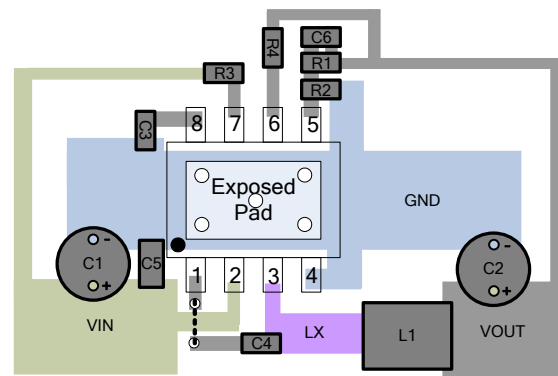
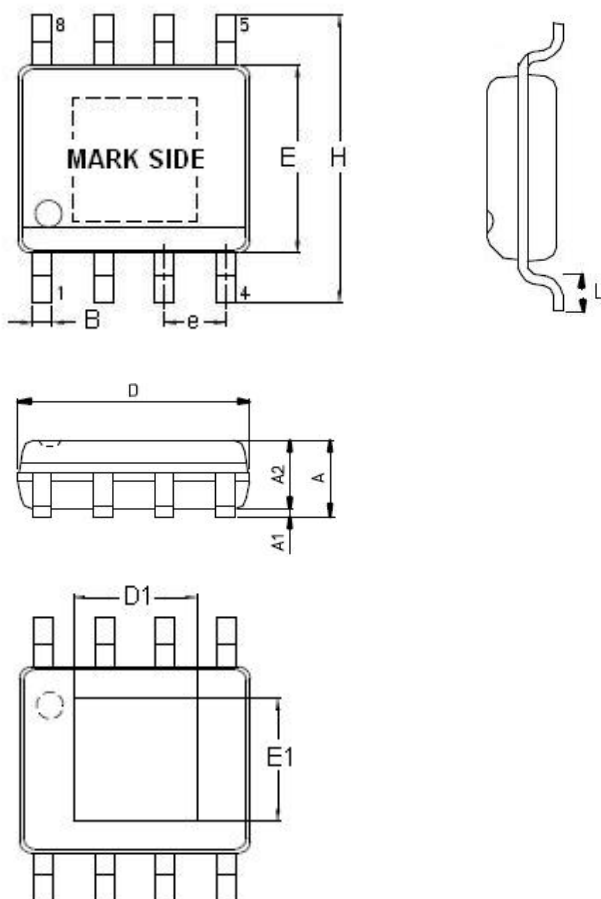


Figure 23. Recommended PCB Layout Diagram

**Outline Information**

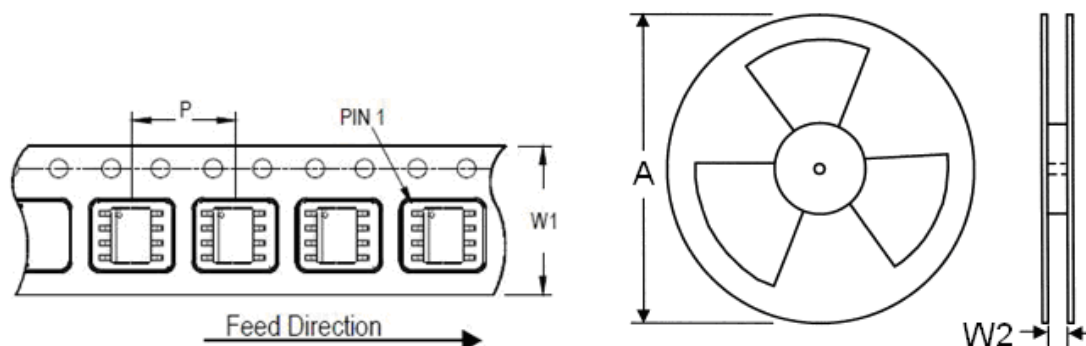
**SOP-8 (Exposed Pad) Package (Unit: mm)**



SYMBOLS UNIT	DIMENSION IN MILLIMETER	
	MIN	MAX
A	1.25	1.70
A1	0.00	0.15
A2	1.25	1.55
B	0.31	0.51
D	4.80	5.00
D1	3.04	3.50
E	3.80	4.00
E1	2.15	2.41
e	1.20	1.34
H	5.80	6.20
L	0.40	1.27

Note : Followed From JEDEC MO-012-E.

**Carrier Dimensions**



Tape Size (W1) mm	Pocket Pitch (P) mm	Reel Size (A)		Reel Width (W2) mm	Empty Cavity Length mm	Units per Reel
		in	mm			
12	8	13	330	12.4	400~1000	2,500

**Life Support Policy**

Fitipower's products are not authorized for use as critical components in life support devices or other medical systems.